

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent application of : <u>Mail Stop Amendment</u>

Hyeong-Seob Kim et al. : Group Art Unit 2818

Serial No. 10/665,630 : Examiner Andy Huynh

Filed September 22, 2003

Title: WAFER LEVEL PACKAGE, MULTI-PACKAGE STACK, AND METHOD OF

MANUFACTURING THE SAME

AMENDMENT

U.S. Patent and Trademark Office Customer Service Window, Mail Stop Amendment Randolph Building 401 Dulany Street Alexandria VA 22314

Sir:

In response to the Office Action of March 2, 2005, please amend the aboveidentified application as follows:

Amendments to the Drawings begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 11 of this paper.